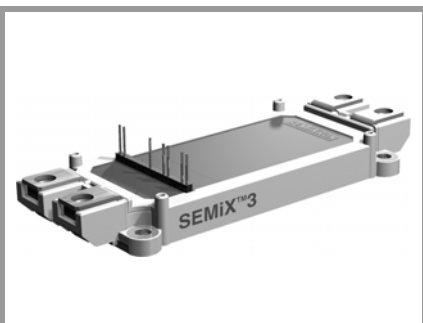


SEMiX403GB128D



SEMiX[®]3

SPT IGBT Modules

SEMiX403GB128D

Preliminary Data

Features

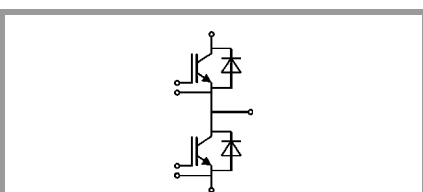
- Homogeneous Si
- SPT = Soft-Punch-Through technology
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability

Typical Applications

- AC inverter drives
- UPS
- Electronic welders up to 20 kHz

Remarks

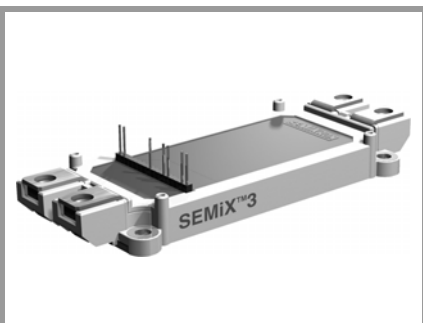
- Not for new design



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Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
IGBT				
V_{CES}			1200	V
I_C	$T_{vj} = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$	420	A
		$T_c = 80^\circ\text{C}$	299	A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$		450	A
V_{GES}			-20 ... 20	V
t_{psc}	$V_{CC} = 600\text{V}$		10	μs
	$V_{GE} \leq 20\text{V}$			
	$T_{vj} = 125^\circ\text{C}$			
	$V_{CES} \leq 1200\text{V}$			
T_{vj}			-40 ... 150	$^\circ\text{C}$
Inverse diode				
I_F	$T_{vj} = 150^\circ\text{C}$	$T_c = 25^\circ\text{C}$	341	A
		$T_c = 80^\circ\text{C}$	234	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$		450	A
I_{FSM}	$t_p = 10\text{ms}$, half sine wave, $T_{vj} = 25^\circ\text{C}$		2000	A
T_{vj}			-40 ... 150	$^\circ\text{C}$
Module				
$I_{t(RMS)}$			600	A
T_{stg}			-40 ... 125	$^\circ\text{C}$
V_{isol}	AC sinus 50Hz, $t = 60\text{s}$		4000	V

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
IGBT						
$V_{CE(sat)}$	$I_{Cnom} = 225\text{A}$ $V_{GE} = 15\text{V}$ chipelevel	$T_{vj} = 25^\circ\text{C}$	1.9	2.35		V
		$T_{vj} = 125^\circ\text{C}$	2.10	2.55		V
V_{CE0}		$T_{vj} = 25^\circ\text{C}$	1	1.15		V
		$T_{vj} = 125^\circ\text{C}$	0.9	1.05		V
r_{CE}	$V_{GE} = 15\text{V}$	$T_{vj} = 25^\circ\text{C}$	4.0	5.3		$\text{m}\Omega$
		$T_{vj} = 125^\circ\text{C}$	5.3	6.7		$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 9\text{mA}$		4.5	5	6.5	V
I_{CES}	$V_{GE} = 0\text{V}$ $V_{CE} = 1200\text{V}$	$T_{vj} = 25^\circ\text{C}$		0.1	0.3	mA
		$T_{vj} = 125^\circ\text{C}$				mA
C_{ies}	$V_{CE} = 25\text{V}$ $V_{GE} = 0\text{V}$	$f = 1\text{MHz}$		20.8		nF
C_{oes}		$f = 1\text{MHz}$		1.38		nF
C_{res}		$f = 1\text{MHz}$		0.87		nF
Q_G	$V_{GE} = -8\text{V} \dots +15\text{V}$			2160		nC
R_{Gint}	$T_{vj} = 25^\circ\text{C}$			1.67		Ω
$t_{d(on)}$	$V_{CC} = 600\text{V}$			145		ns
t_r	$I_{Cnom} = 225\text{A}$ $T_{vj} = 125^\circ\text{C}$			60		ns
				20		mJ
E_{on}	$R_{G on} = 4\Omega$					mJ
$t_{d(off)}$	$R_{G off} = 4\Omega$			575		ns
t_f				70		ns
E_{off}				23		mJ
$R_{th(j-c)}$	per IGBT				0.075	K/W



SEMiX[®]3

SPT IGBT Modules

SEMiX403GB128D

Preliminary Data

Features

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- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability

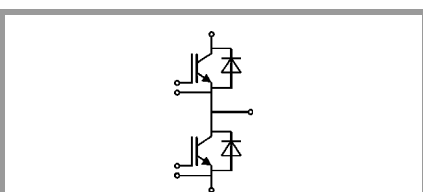
Typical Applications

- AC inverter drives
- UPS
- Electronic welders up to 20 kHz

Remarks

- Not for new design

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
$V_F = V_{EC}$	$I_{Fnom} = 225A$ $V_{GE} = 0V$ chipllevel	$T_{vj} = 25^\circ C$		2.0	2.5	V
		$T_{vj} = 125^\circ C$		1.8	2.3	V
V_{F0}		$T_{vj} = 25^\circ C$	0.75	1.1	1.45	V
		$T_{vj} = 125^\circ C$	0.5	0.85	1.2	V
r_F		$T_{vj} = 25^\circ C$	3.3	4.0	4.7	m Ω
		$T_{vj} = 125^\circ C$	3.6	4.2	4.9	m Ω
I_{RRM}	$I_{Fnom} = 225A$	$T_{vj} = 125^\circ C$		260		A
Q_{rr}	$di/dt_{off} = 4950A/\mu s$	$T_{vj} = 125^\circ C$		29		μC
E_{rr}	$V_{GE} = -15V$ $V_{CC} = 600V$	$T_{vj} = 125^\circ C$		10		mJ
$R_{th(j-c)D}$	per diode				0.13	K/W
Module						
L_{CE}				20		nH
$R_{CC'+EE'}$	res., terminal-chip	$T_C = 25^\circ C$		0.7		m Ω
		$T_C = 125^\circ C$		1		m Ω
$R_{th(c-s)}$	per module			0.04		K/W
M_s	to heat sink (M5)		3		5	Nm
M_t	to terminals (M6)		2.5		5	Nm
w					0.3	kg
Temperature sensor						
R_{100}	$T_c=100^\circ C$ ($R_{25}=5$ k Ω)			0,493 $\pm 5\%$		k Ω
$B_{100/125}$	$R_{(T)}=R_{100}\exp[B_{100/125}(1/T-1/T_{100})]$; $T[K]$;			3550 $\pm 2\%$		K



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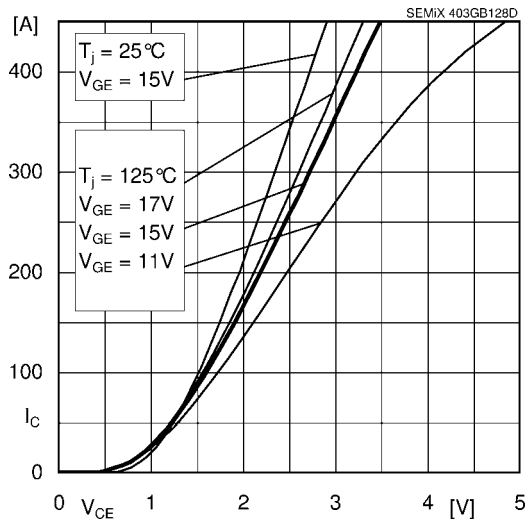


Fig. 1 Typ. output characteristic, inclusive $R_{CC'+EE'}$

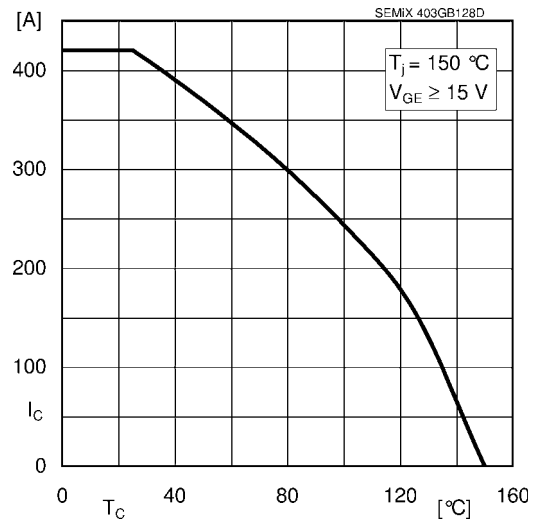


Fig. 2 Rated current vs. temperature $I_c = f(T_C)$

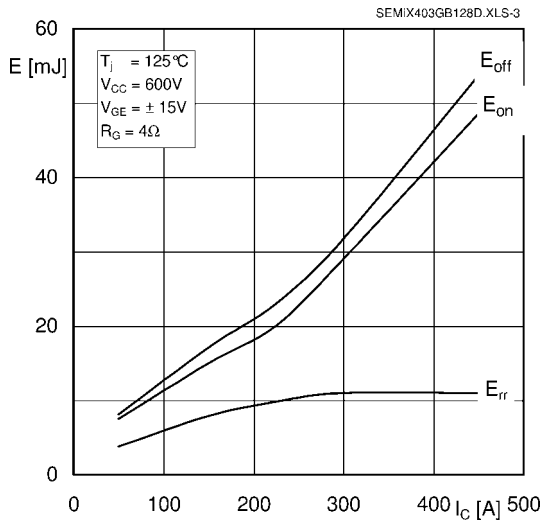


Fig. 3 Typ. turn-on /-off energy = $f(I_c)$

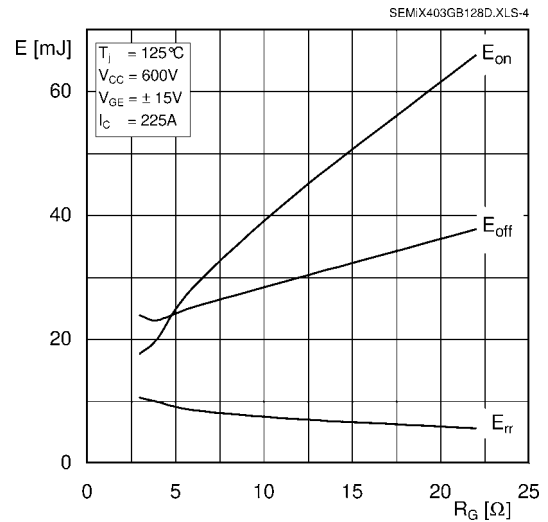


Fig. 4 Typ. turn-on /-off energy = $f(R_G)$

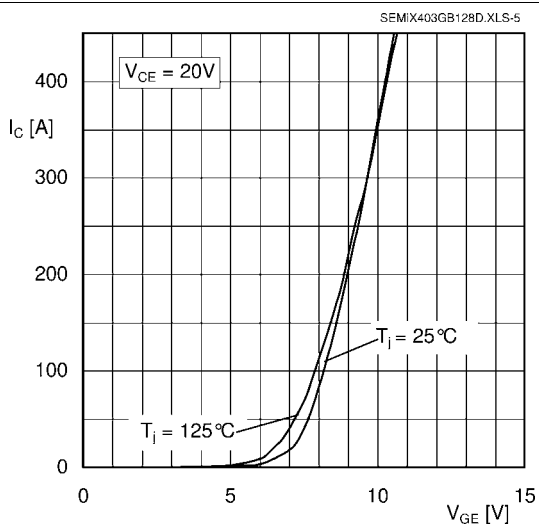


Fig. 5 Typ. transfer characteristic

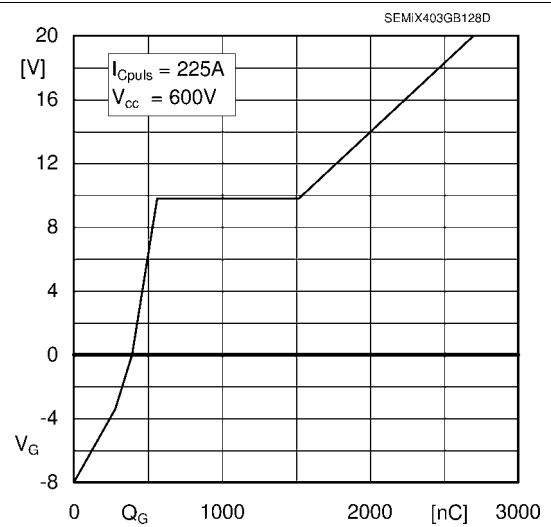


Fig. 6 Typ. gate charge characteristic

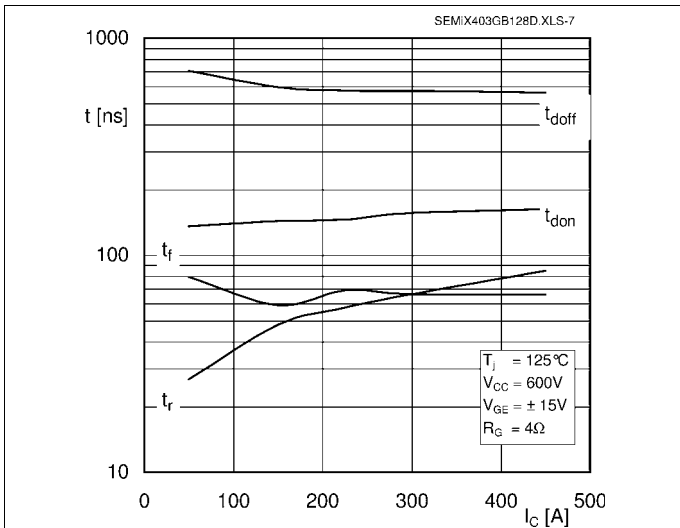


Fig. 7 Typ. switching times vs. I_C

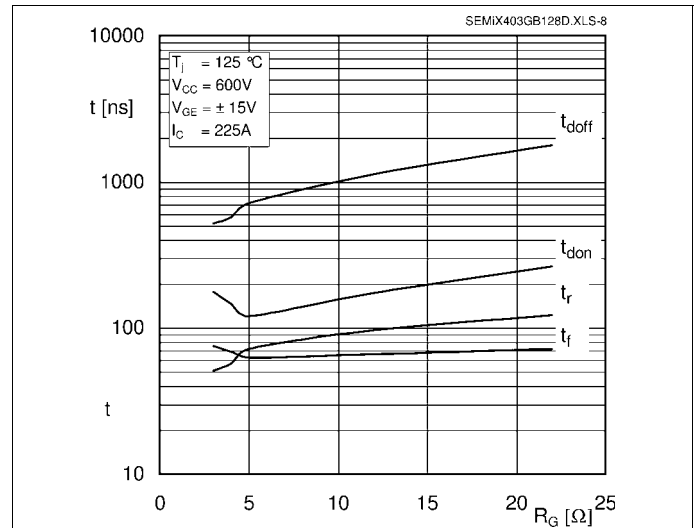


Fig. 8 Typ. switching times vs. gate resistor R_G

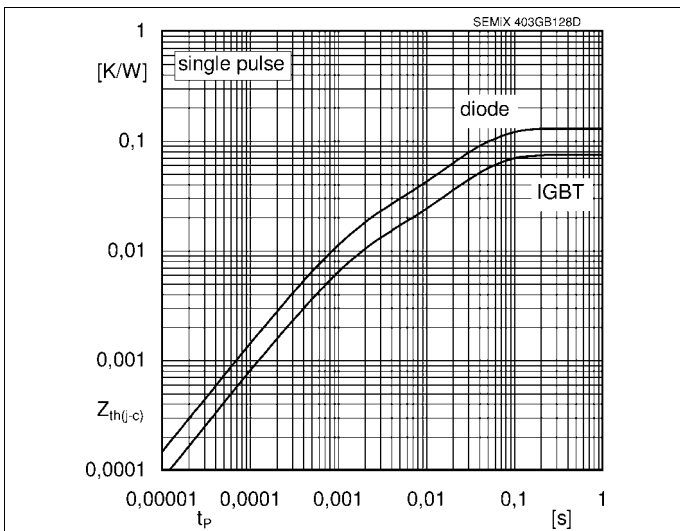


Fig. 9 Typ. transient thermal impedance

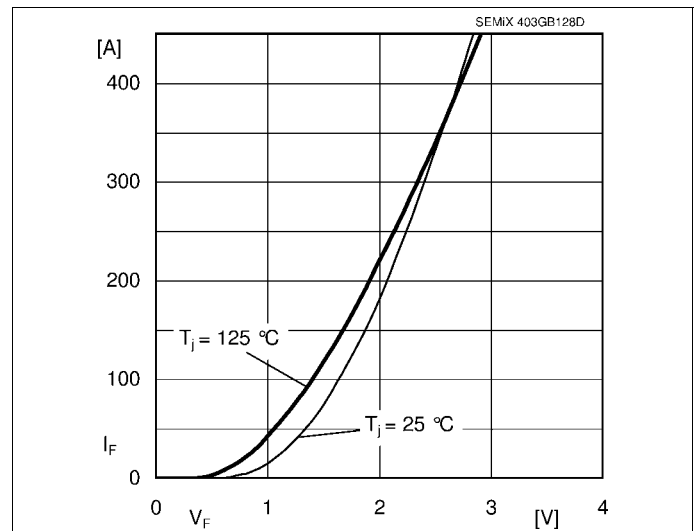


Fig. 10 Typ. CAL diode forward charact., incl. R_{CC+EE}

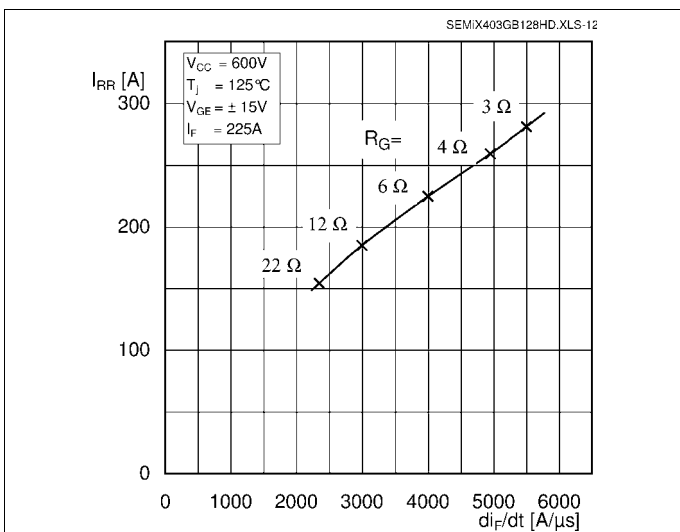


Fig. 11 Typ. CAL diode peak reverse recovery current

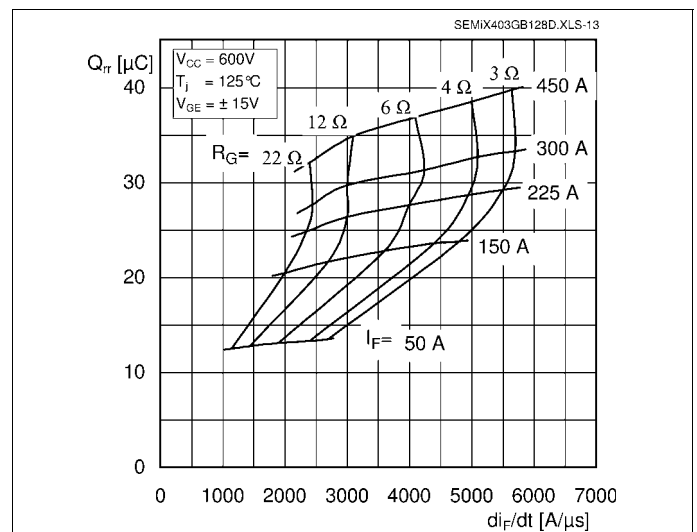
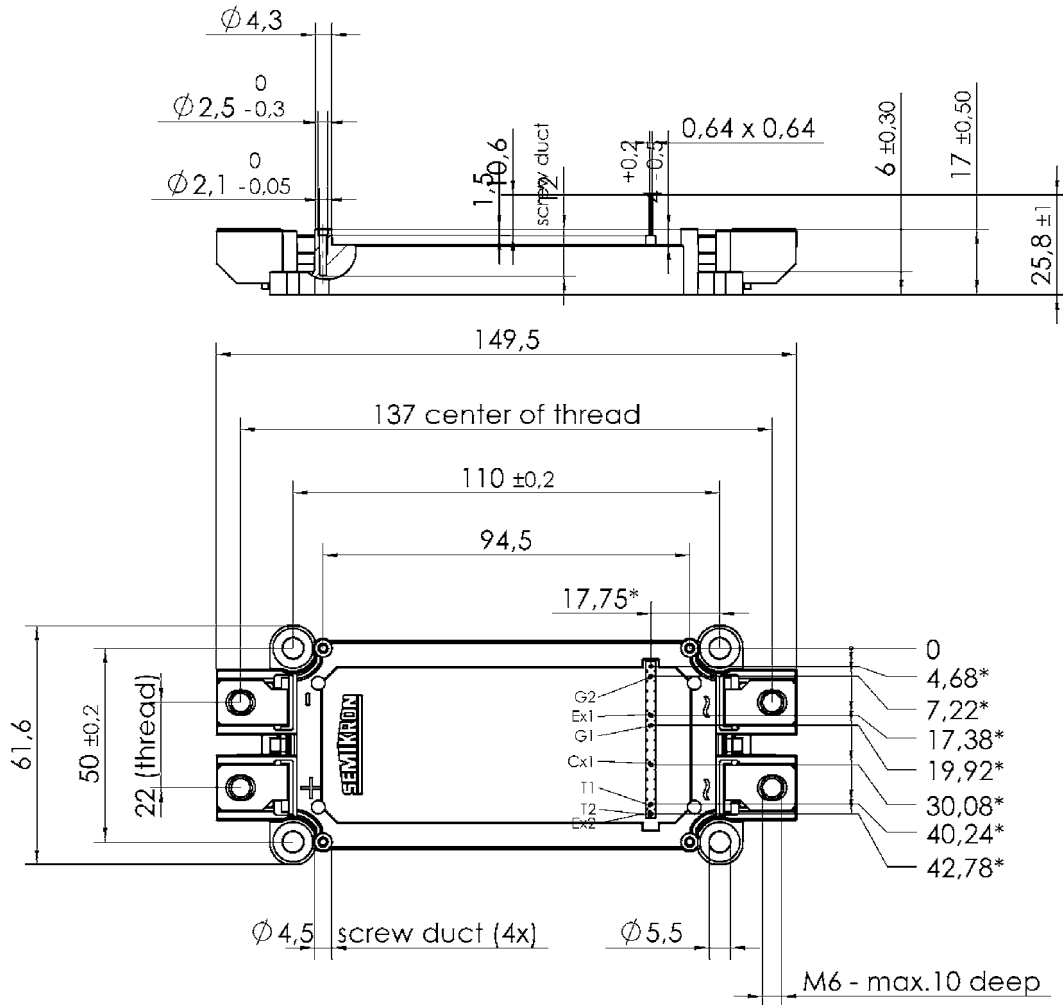


Fig. 12 Typ. CAL diode recovery charge

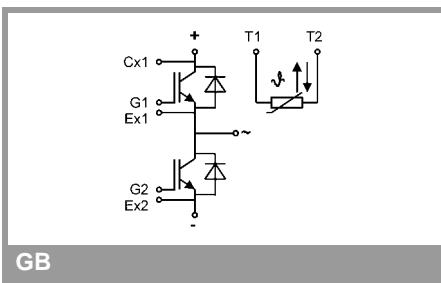
SEMiX403GB128D

case: SEMiX 3



* = all measures with $\phi 0,5$

SEMIX 3



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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

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